

# **Product Specification**

Part Name: 7.0 inch TFT	Module with	Projected	Capacitive '	Touch	Panel
Customer Part ID:					

Topovision Part ID: TVT0700PA-CP

Ver: A

Customer:		
Approved by		

From:	Topovision	Technology	Co., Ltd.
Approved	l by		

#### Notes:

- 1. Please contact Topovision Technology Co., Ltd. before assigning your product based on this module specification
- 2. The information contained herein is presented merely to indicate the characteristics and performance of our products. No responsibility is assumed by Topovision Technology Co., Ltd. for any intellectual property claims or other problems that may result from application based on the module described herein.



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# **Revision History**

Rev.	Date	Contents	Written	Approved
1.0	2013/3/30	Preliminary Specification	Kevin	
1.1	2013/6/21	<ol> <li>Add Weight:205g</li> <li>Add Remark</li> <li>Modify outline drawing from Rev:1.0 to 1.1</li> <li>Release Rev: A for production.</li> </ol>	Anna	
А	2013/11/15	Modify Product Label style.  Modify outline drawing from Rev: 1.1 to A.	Sam	

# Special Notes

- p	
Note1.	
Note2.	
Note3.	
Note4.	
Note5.	



# 3. APPLICATION

DVD player, Car TV, UMPC, POS

# 4. GENERAL SPECIFICATIONS

Composition: 7inch WVGA resolution display with a projected Capacitive Touch Panel (CTP).

Interface LVDS Interface for panel and I<sup>2</sup>C for the CTP.

Parameter	Specifications	Unit
Screen Size	7 (diagonal)	inch
Display Format	1024(H) x (R,G,B) x 600(V)	dot
Finger	5	
LCD Active Area	153.6(H) x 90(V)	mm
CTP Active Area	154.6(H) x 92.4(V)	mm
Pixel Configuration	Stripe	
Outline Dimension	182.6(W) x 117(H) x 5.95(D)	mm
Surface Hardness	Pencil Hardness 7H	
Surface treatment	Glare	
Back-light	LED	
Display mode	Normally white	
Weight	205	g
View Angle direction(Gray inversion)	6 o'clock	
Our components and processes a	re compliant to RoHS standard	

# **5. LCD ABSOLUTE MAXIMUM RATINGS**

Parameter		Symbol	MIN.	MAX.	Unit	Remark
Power supply voltage		VDD	-0.3	5.0	V	
		AVDD	6.5	13.5	V	
		VGH	-0.3	42.0	V	Ta=25°C
		VGL	-20	0.3	V	
		VGH-VGL	-	40	V	
Operating	temperature	e Top -20 60 °C		°C	Module surface*	
Storage te	mperature	Tst -30 70 °C		-		
Humidity Operation			Ta 38°C			
Hulfillulty	Non Operation		Ta 38°C			

# 6. LCD ELECTRICAL CHARACTERISTICS

# **6.1 Operating Conditions**

GND=0V, fH=38.1KHz, fV=60Hz, fCLK=50.2MHz,Ta=25°C

Parameter	Symbol	MIN.	Тур.	MAX.	Unit	Remark
	VDD	3.0	3.3	3.6	V	
Power Supply voltage	AVDD	10.8	11	11.2	V	
Fower Supply voltage	VGH	19.7	20	20.3	V	
	VGL	-6.5	-6.8	-7.1	V	
Input signal voltage	VCOM	2.7	3.7	4.7	V	Note3
Differential Input High Threshold	RxVTH	-	-	100	[mV]	RxVCM=1.2V
Differential input Low Threshold	RxVTL	-100	-	-	[mV]	Note 2

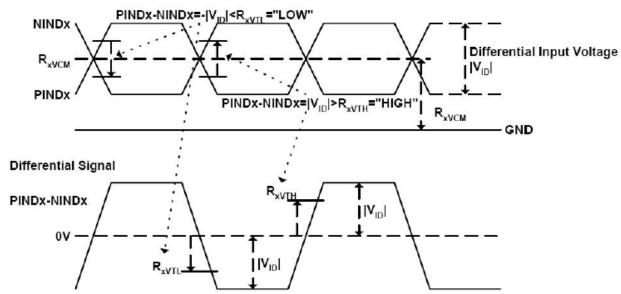


_							
Input voltage range (singled-end)	RxVIN	0	-	2.4	V		
Differential input common mode voltage	RxVCM	VID /2	-	2.4- VID /2	V		
Differential voltage	[VID]	0.2	-	0.6	V		
Differential input leakage current	RVxliz	-10	-	+10	uA		
"H" level logical input voltage	VIH	0.7VDD	-	VDD	V	Note1	
"L" level logical input voltage	VIL	0	-	0.3 VDD	V	Note	

Note 1: LVDS, Reset.

Note 2: LVDS Signal Waveform.

### Single-end Signals



Note 3: Typical VCOM is only a reference value, it must be optimized according to each LCM. Be sure to use VR;

# **6.2 Current Consumption**

Parameter	Symbol	MIN.	TYP.	MAX.	Unit	Remark			
Current for Driver	lgн	-	0.25	1.0	mA	VGH=20V			
	IGL	-	0.25	1.0	mA	VGL=-6.8V			
	Ivdd	-	38	60	mA	VDD=3.3V			
	lavdd	-	20	30	mA	AVDD=11V			

# **6.3 Backlight Driving Consumption**

Ta= 25 °C

Parameter	Symbol	Min.	Тур.	Max.	Unit	Remark
LED voltage	$V_L$	-	9.3	10.2	V	Note 1
LED current	Ι <sub>L</sub>	-	180	190	mA	
LED life time	-	-	20000	-	hr	Note 2

Note 1: The LED Supply Voltage is defined by the number of LED at Ta=25 and IL =180mA.

Note 2: The "LED life time" is defined as the module brightness decrease to 50% original brightness at Ta=25 and IL =180mA. The LED lifetime could be decreased if operating IL is lager than 160mA.



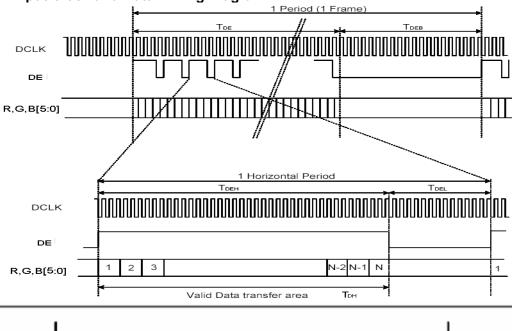
# 7. LCD TIMING SPECIFICATIONS

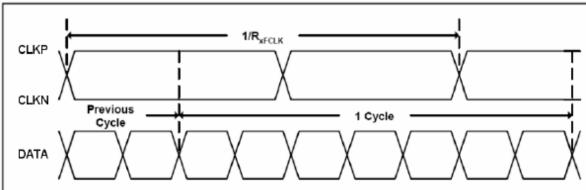
# 7.1 AC Characteristics

# 7.1.1 AC Electrical Characteristics

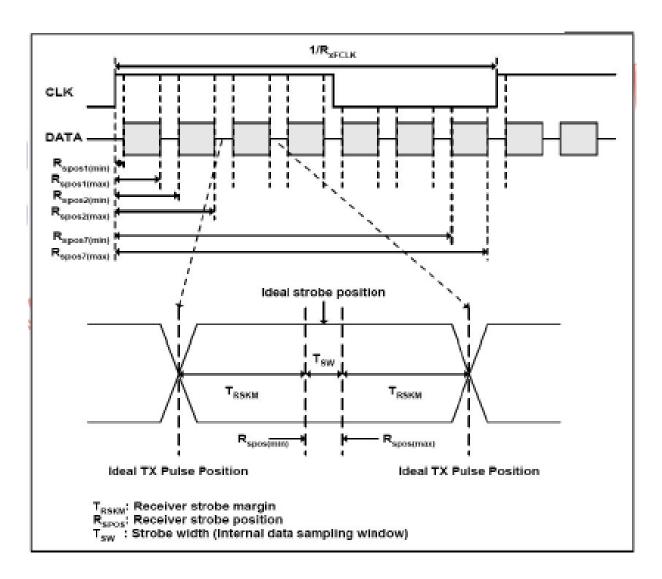
Parameter	Symbol	MIN.	Тур.	MAX.	Unit	Remark
Clock Frequency	RxFCLK	40.8	51.2	67.2	MHz	Frame rate =60Hz
Input data skew margin	TRSKM	500	-	-	ps	
Clock high time	TLVCH	-	4/(7*RxFCLK)	-	ns	
Clock low time	TLVCL	-	3/(7*RxFCLK)	-	ns	
Horizontal display area	TDEH	-	1024		RxFCLK	
HS period time	TDEH+TDEL	1114	1344	1400	RxFCLK	
HS Blanking	TDEL	90	320	376	RxFCLK	
Vertical display area	TDE	-	600	-	TDEH+TDEL	
VS period time	TDE+TDEB	610	635	800	TDEH+TDEL	
VS Blanking	TDEB	10	35	200	TDEH+TDEL	

# 7.1.2 Input Clock and Data Timing Diagram





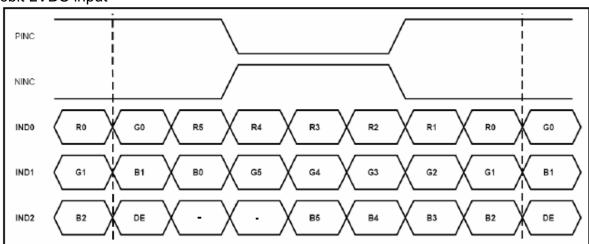




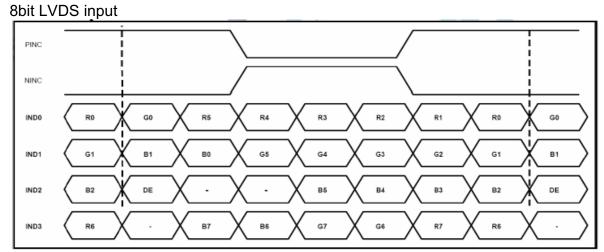
# 7.2 Timing Controller Timing Chart

# 7.2.1 Data Input format

# 6bit LVDS input







Note: Support DE timing mode only, SYNC mode not supported

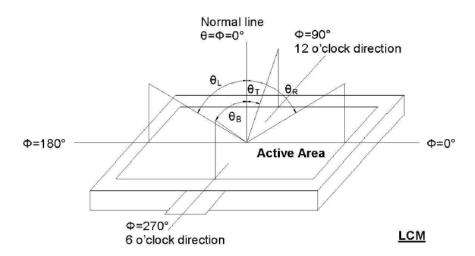
# 8. OPTICAL CHARACTERISTIC

Parameter		Symbol	Condition	MIN.	TYP.	MAX.	Unit	Remarks	
		θL		-	75	-	deg		
Viewing	Viewing		Center	-	75	-		Note 1,3	
Angle		θТ	CR≥10	-	70	-		Note 1,5	
		θВ		-	75	-			
Contrast Ratio		CR	at optimized viewing angle	500	700	-		Note 3,4	
Response time	Rise	Tr	Center	-	10	20	ms	Note 2.6	
Response une	Fall	Tf	θ <b>x</b> =θ <b>y</b> =0°	-	15	30	ms	Note 3,6	
Uniformity		B-uni	$\theta x = \theta y = 0^{\circ}$	70	-	-	%	Note 3,5	
Brightness		L	θ <b>x</b> =θ <b>y</b> =0°	-	420	-	cd/	Note 2,3	
Chromaticity		X <sub>W</sub>	Center	0.26	0.31	0.36		Note 2,3,7	
Cilionialicity		y <sub>w</sub>	θ <b>x</b> =θ <b>y</b> =0°	0.28	0.33	0.38		111016 2,3,1	
Image sticking		tis	2 hours	-	-	2	sec	Note 8	

The following optical specifications shall be measured in a darkroom or equivalent state (ambient luminance  $\leq 1$  lux, and at room temperature). The operation temperature is  $25^{\circ}C\pm2^{\circ}C$  and LED Backlight Current IL=180mA. The measurement method is shown in Note1.

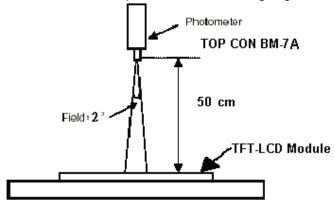
Note 1: Definition of viewing angle range





Note 2: All input terminals LCD panel must be ground while measuring the center area of the panel. The LED driving condition is IL=180mA .

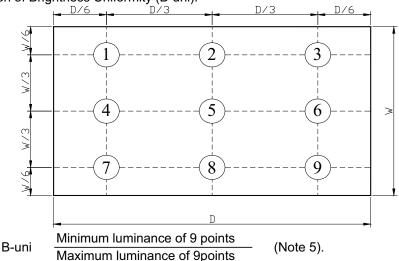
Note 3: Measured at the center area of the panel and at the viewing angle of the  $\theta x=\theta y=0^{\circ}$ 



Note 4: Definition of Contrast Ratio (CR):

CR = Luminance with all pixels in white state
Luminance with all pixels in Black state

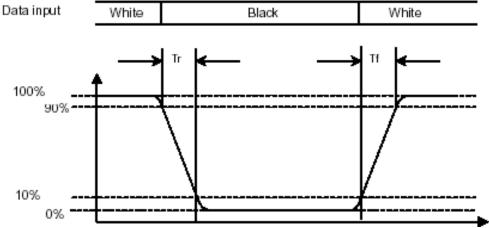
Note 5: Definition of Brightness Uniformity (B-uni):





### Note 6: Definition of Response Time:

The Response Time is set initially by defining the "Rising Time (Tr)" and the "Falling Time (Tf)" respectively. Tr and Tf are defined as following figure.



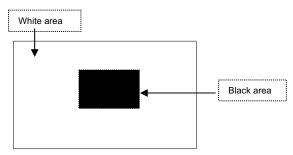
Note 7: Definition of Chromaticity:

The color coordinate (x<sub>w</sub>,y<sub>w</sub>) is obtained with all pixels in the viewing field at white state.

# Note 8: Definition of Image sticking (tis):

Continuously display the test pattern shown in the figure below for 2 hours. Then display a completely white screen. The previous image shall not persist more than 2 sec at 25  $^{\circ}$ C

#### Image sticking pattern





# 9. PIN CONNECTIONS

Pin No	Symbol	Description	Remark
1	VCOM	Common Voltage	
2	VDD	Power Voltage for digital circuit	
3	VDD	Power Voltage for digital circuit	
4	NC	No connection	
5	Reset	Global reset pin	
6	STBYB	Standby mode, Normally pulled high STBYB = "1", normal operation STBYB = "0", timing controller, source driver will turn off, all output are High-Z	
7	GND	Ground	
8	RXIN0-	- LVDS differential data input	
9	RXIN0+	+ LVDS differential data input	
10	GND	Ground	
11	RXIN1-	- LVDS differential data input	
12	RXIN1+	+LVDS differential data input	
13	GND	Ground	
14	RXIN2-	- LVDS differential data input	
15	RXNI2+	+LVDS differential data input	
16	GND	Ground	
17	RXCLKIN-	- LVDS differential data input	
18	RXCLKIN+	+ LVDS differential data input	
19	GND	Ground	
20	RXIN3-	- LVDS differential data input	
21	RXIN3+	+ LVDS differential data input	
22	GND	Ground	
23	NC	No connection	
24	NC	No connection	
25	GND	Ground	
26	NC	No connection	
27	DIMO	Backlight CABC controller signal output	
28	SELB	6bit/8bit mode select	Note 1
29	AVDD	Power for Analog Circuit	
30	GND	Ground	
31	LED-	LED Cathode	
32	LED-	LED Cathode	
33	L/R	Horizontal inversion	Note 3
34	U/D	Vertical inversion	Note 3
35	VGL	Gate OFF Voltage	
36	CABCEN1	CABC H/W enable	Note 2
37	CABCEN0	CABC H/W enable	Note 2
38	VGH	Gate ON Voltage	



39	LED+	LED Anode	
40	LED+	LED Anode	

Note 1: If LVDS input data is 6 bits ,SELB must be set to High;

If LVDS input data is 8 bits ,SELB must be set to Low.

Note 2: When CABC\_EN="00", CABC OFF.

When CABC\_EN="01", user interface image.

When CABC\_EN="10", still picture. When CABC\_EN="11", moving image.

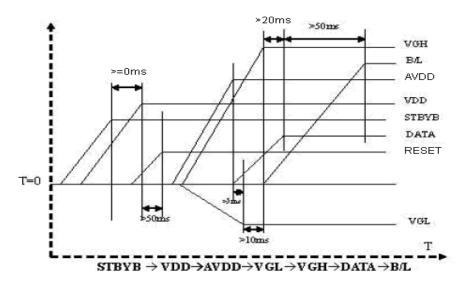
When CABC off, don't connect DIMO, else connect it to backlight.

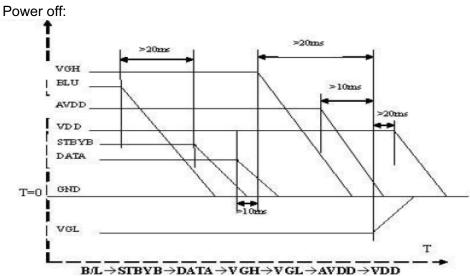
Note 3: When L/R="0", set right to left scan direction.
When L/R="1", set left to right scan direction.
When U/D="0", set top to bottom scan direction.

When U/D="1", set bottom to top scan direction.

## 9.1 power ON/OFF sequence:

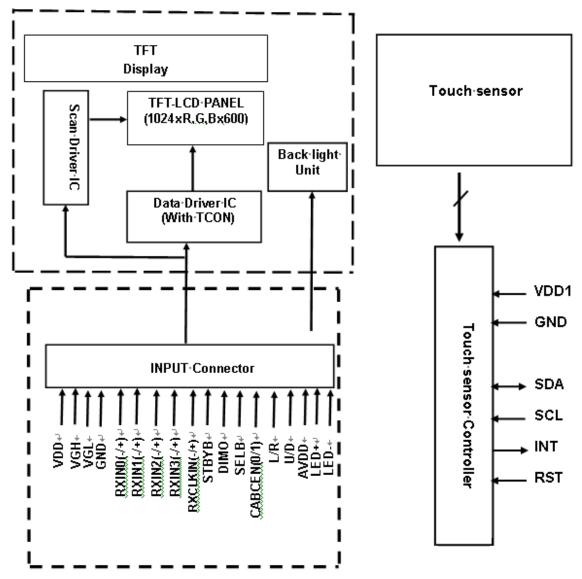
#### Power on:







# 10. BLOCK DIAGRAM





# 11. CTP SPECIFICATIONS

# 11.1 ABSOLUTE MAXIMUM RATINGS

Symbol	Description	Min	Тур.	Max	Unit
VDD1	Supply voltage	-0.3	-	3.6	V
Vı	Logic input voltage	-0.3	-	VDD1+0.3	V

# 11.2 ELECTRICAL CHARACTERISTICS

Symbol	Description	Min	Тур.	Max	Unit
VDD1	Supply voltage	2.5	3.3	3.6	V
GND	Supply voltage	-	0	-	V
VIH	Input H voltage	0.8VDD1	-	VDD1	V
VIL	Input L voltage	0	-	0.2VDD1	V

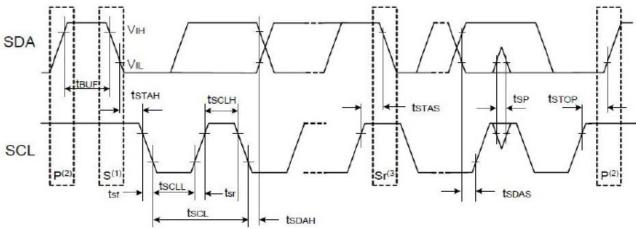
11.3 Power consumption

Symbol	Description	Fingers	F <sub>scan</sub> (Hz)	Min	Тур.	Max	Unit
		1	130	-	-	4	mA
		2	60	-	-	5	mA
IVDD1	Active mode	3	50	-	-	5.2	mA
		4	45	-	-	5.4	mA
		5	40	-	-	5.6	mA
lata an	Sleep mode	0	10	-	-	0.11	mA
Isleep	Deep sleep mode	-	-	-	-	50	uA
Ifreeze	Freeze mode	-	-	-	-	2	uA
	Boot load	-	-	-	-	6.2	mA
	Calibration	-	-	-	-	6.2	mA

# 11.4 CTP Interface and Data Format [Slave address is 0x5C ( 7 bit addressing )]

Communication protocol: I<sup>2</sup>C

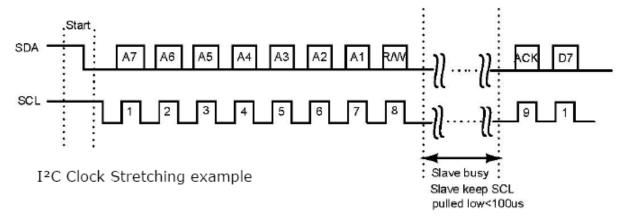
Clock frequency: 100 KHz (400 KHz Fast mode)



Note (1) Start Condition;(2)Stop Condition;(3)Retransmit start condition



Symbol	Description	Min	Max	Unit
tscl	SCL input cycle time	12tcyc+600	-	
tsclh	SCL input H width	3tcyc+300	-	
tscll	SCL input L width	5tcyc+500	-	
tsF	SCL, SDA input fall time	-	300	
tsp	SCL, SDA input spike pulse rejection time	-	1 tcyc	
tsuf	SDA input bus-free time	5tcyc	-	ns
tstah	Start condition input hold time	3tcyc	-	
tstas	Retransmit start condition input setup time	3tcyc	-	
tstop	Stop condition input setup time	3tcyc	-	
tsdas	Data input setup time	1tcyc+40	-	
tsdah	Data Input hold time	10	-	



The protocol for data exchange has been designed with the following considerations

- 1 Most of the data traffic is read operation to get the finger or fingers position
- 2 Read operations do need an initial write operation.
- 3 Write operations are most of the time power management and interrupt setting instructions
- 4 Interrupt pulse width setting adjustments need a write operation.

S	START
Р	STOP
Α	Acknowledge
N	No acknowledge
W	WRITE
R	READ
DATA	8-bit

From slave to Master

From Master to Slave



# 11.5 Timing Characteristic

#### **Read Operation**

Read packets have variable content length, decided by the host. It is available to do a single read operation or a sequential read operation. Therefore, the beginning register address is needed to set before a read operation. And the data sent exactly follow the register table 9, table 11, table 12, and table 15. And, the firmware in the slave will use a memory copy of the register for I<sub>2</sub>C slave read operation, so that firmware can continue updates, and I<sub>2</sub>C slave is still using a consistent (but old) coordinates for read operation as below:



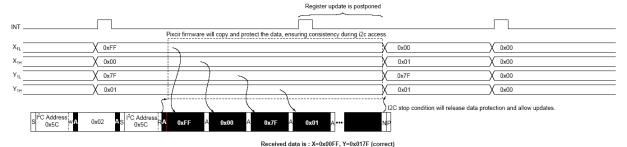
## Read operation

In a sequential read operation, the first data sent by the MSI device is therefore the touching register, and then the X and Y coordinates of the first finger, then 2nd finger, 3<sup>rd</sup> finger, 4th finger and then coordinates of the 5th finger, and so on. Refer in below:

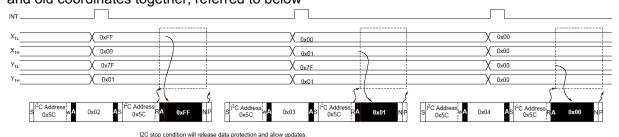


## Coordinates read operation

If the host does not finish the read operation when the INT line is set again, the slave firmware will delay to update coordinates registers for I<sup>2</sup>C read operation until the host finish the read operation referred to below



I<sup>2</sup>C stop condition will release data protection and allow the slave firmware update the coordinates registers for I<sup>2</sup>C read operation. So, the host has the change to give incorrect data when it gets the coordinates data with single read operation. Because the host sends many times for I<sup>2</sup>C stop condition in each multi-fingers coordinate's position reading, it will give the slave firmware chance to update the coordinates registers for I<sup>2</sup>C read operation, the host will give a combine unrelated data combines new and old coordinates together, referred to below



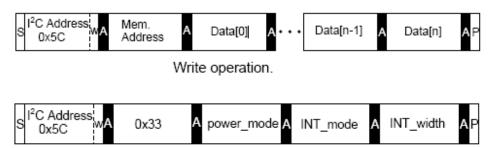
Coordinates read operation explanation

Received data is: X=0x01FF, Y=0x0000



### **Write Operation**

Write packets have variable content length, decided by the host. Write operation stops when host issues an I<sub>2</sub>C STOP symbol. The write packet is illustrated in below. Following the I<sub>2</sub>C device address, the first byte of the write packet is always the destination register address, referred in table 9, table 11, table 12, and table 15. Subsequent data values are written at the register pointed by the address, immediately upon reception of the byte. The address counter is automatically incremented. Subsequent data bytes are treated in continuation of the writing operation.



Write mode setting operation .

Note1: MSI Registers

Address	Туре	Name	Description	Category
0	char	touching	Bitfield, see table 10	
1	char	buttons	Buttons bitfield	1
2 (lsb)	int	posx1	Finger #1 X position	1
3 (msb)				
4 (lsb)	int	posy1	Finger #1 Y position	1
5 (msb)				
6	char	id1	Finger #1 identificator	
7 (lsb)	int	posx2	Finger #2 X position	]
8 (msb)				
9 (lsb)	int	posy2	Finger #2 Y position	]
10 (msb)				touch
11	char	id2	Finger #2 identificator	louch
12 (lsb)	int	posx3	Finger #3 X position	]
13 (msb)				
14 (Isb)	int	posy3	Finger #3 Y position	1
15 (msb)				
16	char	id3	Finger #3 identificator	1
17 (lsb)	int	posx4	Finger #4 X position	1 1
18 (msb)				
19 (lsb)	int	posy4	Finger #4 Y position	1
20 (msb)				
21	char	id4	Finger #4 identificator	1
22 (Isb)	int	posx5	Finger #5 X position	1
23 (msb)				
24 (lsb)	int	posy5	Finger #5 Y position	1 1
25 (msb)				
26	char	id5	Finger #5 identificator	1 1
27	char	strength1	Finger #1 strength	]
28	char	strength2	Finger #2 strength	]
29	char	strength3	Finger #3 strength	]
30	char	strength4	Finger #4 strength	]
31	char	strength5	Finger #5 strength	



Bit 0,1,2	Nb of fingers touching (NBF)
Bit 3	Noise flag (indicates the report is unreliable) (NOI)
Bit 4	message flag (indicates a message string is sent by slave) (MSG)
Bit 5	buffer indicates the master has missed more than 2 reports, which are
	stored in buffer array (BUF)
Bit 6	palm flag (indicates the algorithm has a palm or similar blocking issue) (PAL)
Bit 7	water flag, indicates the algorithm has a rejected inputs due to water (WAT)

Address	Туре	Name	Description	Category
32 (lsb) 33 (msb)	int	initial_distance	Distance separating fingers on the first time multitouch is detected	gesture
34 (lsb) 35 (msb)	int	distance	Distance separating fingers	
36 (lsb) 37 (msb)	int	ratio	100-distance / initial_distance	
38	char	water_level		
39	char	noise_level		
40	char	palm_level		monitor
41	char	signal_x		
42	char	signal_y		]
43	char	button1	Signal level of the buttons	buttons
50		button8		
51	char	power_mode	Power management register. See §2.2.3 and table 16	power
52	char	INT_mode	Control of the ATTb pin, see §2.2.4 and table 17	management
53	char	INT_width	ATTb pulse width	
54-57	char		reserved for future use	
58	char	SPECOP	Special operation . See table 13	special
59 (lsb) 60 (msb)	int	EEPROM_read_ad	Address used during special operation	operations
61	char	Engineering_cmd	Allows, with I <sup>2</sup> c, to send "hyperterminal like commands" for engineering modes	
62 (lsb) 63 (msb)	int	CRC	FLASH CRC value (must be requested by SPECOP), excluding "EEPROM" zone	version
64-95	char	version[031]	Customer version control (32bytes) (imap to "eeprom")	



96-135	char	message[039] Null terminated ASCII message string for engineering and debug purpose		
136 (lsb) 137 (msb)	int	RAW_CTRL Controls RAW data mode (intern raw, etc) see table 14		
138	char	cross_x	X coordinate for method 1 crossing node measurement request	method 1
139	char	cross_y	Y coordinate for method 1 crossing node measurement request	Inculou I
140 (lsb) 142 (msb)	int	cross_node	node Measurement result for method 1	
142 (lsb) 143 (msb)	int	RAW[069]	Raw data, content controlled by RAW_CTRL register, or alternatively, history buffer (see below)	RAW data
144 (Isb) 145 (msb) etc.	int int	shared with history_buffer	,	

0	Normal operation
1	"EEPROM" read operation, start address must be written in EEPROM_read_addr
2	"EEPROM" write operation NOT IMPLEMENTED
3	Calibration
4	CRC checksum of the application in Flash

Bit 0	Choose function (0: history buffer, 1: RAW data, 2: system info) See table 15	
Bit 1	Choose function (o. history buller, 1. RAW data, 2. system into) See table 15	
Bit 2	Method (0 0r 1)	
Bit 3	Show offset correction (and low-pass fiter for M0)	
Bit 4	Show m0 sensitivity adjustment (bit3 must also be set)	
Bit 5	M1 pattern small (0) or pattern large (1)	
Bit 6	M1 sense direction (0:Y,1:X)	
Bit 7	M1 band scan. if 0, only report a single cross node. If 1,report a full X axis	
	scan at RAW position	
Bit 8	Disable Algorithm	
Bit 9	Enable single shot RAW refresh, must be set to 1 and bit9 to 0. Auto back to	
	0 and bit9 to 1 after single shot is done	
Bit 10	Refresh frozen after single shot is done when 1. Set to 0 to release the	
	freeze and go back to normal refreshing	
Bit 11		
Bit 12		
Bit 13		
Bit 14		
Bit 15		



Address	Type	Name	Description	Category
142	char	interval	interval  Subsampling rate when filling the history buffer. Disable: 0. Keep all points: 1. Keep one out of two: 2. Etc.	
143	char	buffer_level	buffer_level Number of fingers report in the buffer	
144 (lsb) 145 (msb)	int	posx	Coordinate X of the reported point, at time=0	
146 (Isb) 147 (msb)	int	posy	Coordinate Y of the reported point, at time=0	
148 (lsb) 149 (msb)	int	posx	Coordinate X of the reported point at time=1	
150 (lsb) 151 (msb)	int	posy	Coordinate Y of the reported point at time=1	
298 (lsb) 299 (msb)	int	posx	Coordinate X of the reported point, at time=19	
300 (lsb) 301 (msb)	int	posy	Coordinate Y of the reported point, at time=19	

# 11.6 Operating Mode Register

11.6.1 POWER\_MODE Register

11.6.1 POWER_MODE Register			
Address	Name	Description of POWER_MODE Register	
7-4		Refer to ALLOW_SLEEP function description	
		Idle_period_time = k * 16 * Active_scan_period_time [s], with	
	IDLE_PERIOD[3-0]	k = value of IDLE_PERIOD[3-0]	
		Active_scan_period_time = duration [s] of a scan period in active	
		mode.	
3	-	Not used	
		Allow self demotion from active to sleep mode, provide that this	
		flag is set. If the MSI device is in active mode and no fingers is	
2	ALLOW_SLEEP	detected for more than IDLE_PERIOD time, then it allow AUTO	
	_	JUMP to sleep mode. If this flag is not set, the host must	
		explicitly switch the device from active to sleep mode.	
		Power mode setting of the MSI device:	
		00:Active Mode	
1-0	POWER_MODE[1-0]	01:Sleep Mode	
		10:Deep Sleep Mode	
		11:Freeze Mode	



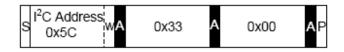
11.6.2 INT MODE Regist	er
------------------------	----

Address	Name	Description
7-4	-	Not used
3	EN_INT	0:disable interrupt mode 1:enable interrupt mode
2	INT_POL	0:the interrupt is low active(default) 1:the interrupt is high active
1-0	INT_MODE[1-0]	00:INT assert periodically 01:INT assert only when finger moving 10:INT assert only when finger touch(default)

### 11.6.3 Power management

#### **Active mode**

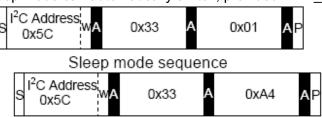
In this mode, the slave resumes with a new scan directly after each I<sup>2</sup>C transfer (after INT rising edge). This is used to reach the highest refresh rate, but also has the highest current consumption. Below shows how to force the slave into Active mode.



Active mode sequence

#### Sleep mode

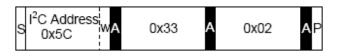
This mode is selected to decrease the current consumption during low activity phases on the sensor, which need a lower refresh rate(10Hz). The MSI can automatically switch to Active mode(when finger is detected, provided that ALLOW\_SLEEP bit is set in the POWER\_MODE register) or by set POWER\_MODE register. Also, the MSI can automatically switch from Active to Sleep mode when no finger is detected for more than IDLE\_PERIOD time, provided that ALLOW\_SLEEP bit is set in the POWER\_MODE register. Figure 44 shows how to force the slave into Sleep mode. Below shows how to force the slave into Sleep mode can automatically switch, provided IDLE\_PERIOD=10.



Sleep mode automatically switch sequence

#### Deep Sleep mode

This mode is selected to achieve the minimum consumption during very low activity phases on the sensor, which need a lowest refresh rate (1Hz). The MSI only can switch to Deep Sleep mode by set POWER\_MODE register. Below shows how to force the slave into Deep Sleep mode.



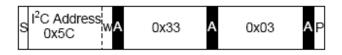
Deep Sleep mode sequence



#### Freeze mode

In this mode, the slave MCU internal clock source is stopped, and consumption is only MOS leakage. Below shows how to force the slave into Freeze mode. There are two ways to wake up from freeze mode.

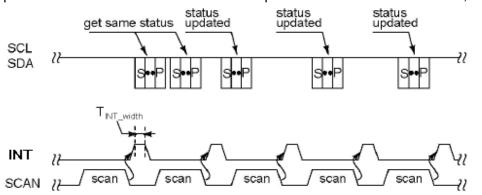
- RST pin pull down (connect to the Ground) (default)
- INT pin change ("1 to 0" or "0 to 1")



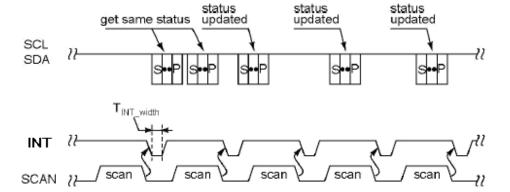
Freeze mode sequence

#### 11.6.4 Transition of INT line

When INT\_MODE=00 in the INT MODE register, the slave will set the INT line with INT\_width pulse width after each scan in order to request the attention from the host, as shown in below



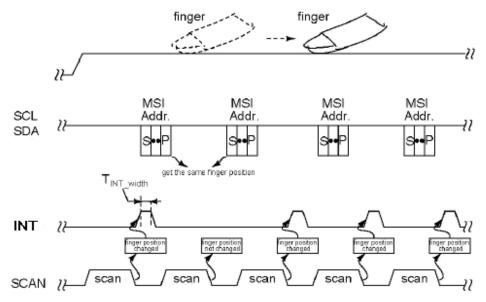
INT line pull up by slave (INT\_POL=1, INT\_MODE=00 in the INT mode register)



INT line pull down by slave (INT\_POL=0, INT\_MODE=00 in the INT mode register)

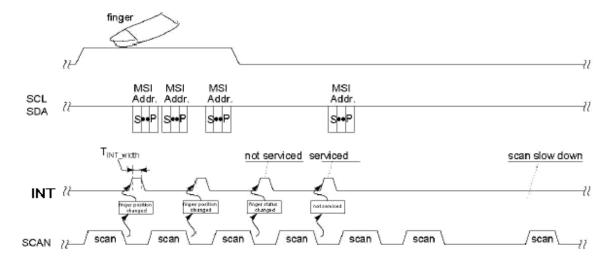
When INT\_Mode=01 in the INT mode register and finger moving on the panel, the slave will set The INT line after each scan, as shown in below.





INT line pull up when finger moving (INT\_POL=1, INT\_MODE=01 in the INT mode register)

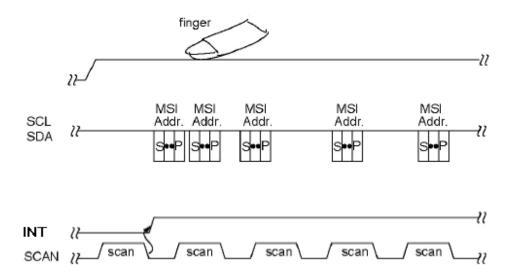
When fingers leaves the panel, the slave will continue to pulse INT line for each scan; but once the master has serviced this request and become now aware that there is no more finger touching, the slave will stop pulse the INT line, and will also gradually reduce the scan speed, as shown in below



INT line will stop pulse when finger leaves and master has acknowledge the situation (INT\_POL=1 in the INT mode register)

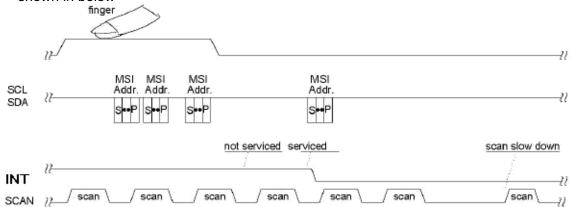
When INT\_Mode=10 in the INT mode register and finger touch the panel, the slave will set The INT line after each scan as shown in below.





INT line pull up when finger touch (INT POL=1, INT MODE=10 in the INT mode register)

When fingers leaves the panel, the slave will continue keep INT line status for each scan; but once the master has serviced this request and become now aware that there is no more finger touching, the slave will release the INT line, and will also gradually reduce the scan speed, as shown in below



INT line will stop pulse when finger leaves and master has acknowledge the situation (INT\_POL=1 in the INT mode register)

# 11.7. PIN CONNECTIONS

No.	Name	I/O	Description	
1	VDD1	Ρ	Power;(VDD1=3.3V)	
2	GND	Р	Ground	
3	RST	I	Reset, active high	
4	SCL	l	I2C clock input	
5	SDA	I/O	I2C data signal	
6	INT	0	Interrupt output	
7	NC		No connect	
8	NC	-	No connect	



# 11.8 CTP Life Test

	• • • • • • •		
			central point
		> 1,000,000 Use 8 mm diameter silicon	
1	1 Point hitting life	rubber/force 3N to knock on the same point twice	
		per second (no-operating), after test function check	
		pass.	
2	Line Drawing life (no contact CTP)	> 100,000; Use 11mm diameter/copper column to draw straight lines back and forth as the following red lines at the speed of 100mm/sec under system operating.	



# 12. Appearance Specification

# 12.1 Inspection and Environment conditions

12.1.1 Temperature: 25± 5

12.1.2 Humidity: 55 ± 10% RH

12.1.3 Light source: Fluorescent Light

12.1.4 Inspection: Viewing distance: 35±5cm

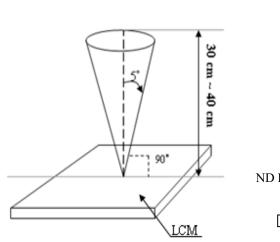
12.1.5 Ambient Illumination:

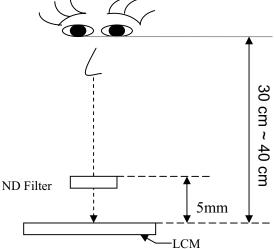
(1) Cosmetic Inspection: 500 ~ 800 lux (2) Functional Inspection: 400 ~ 600 lux

12.1.6 Inspection View angle:

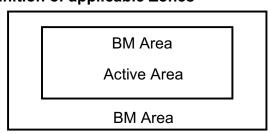
(1) Inspection under operating condition: ±5°

(2) Inspection under non-operating condition: ± 45°





# 12.2 Definition of applicable Zones



### 12.3 Judgment standard

The Judgment of the above test should be made after exposure in room temperature for two hours as follow:

Pass: Normal display image with no obvious non-uniformity and no line defect. Partial transformation of the module parts should be ignored.

Fail: No display image, obvious non-uniformity, or line defect.



12.4 Cosmetic Specification and Inspection Items

Inspection Item	Inspection Criteria	Illustration
Display function	No Display malfunction	
Contrast ratio	Does not meet specified range in the spec.	(Major) (Note:2)
Line Defect	No obvious Vertical and Horizontal line defect in black and White.	
Point Defect	ItemAcceptable number numberTotalBright25Dark45Two adjacent dot22	One Dot  Two adjacent dot
Foreign material (Black or White spots shape)	Zone Acceptable Class of number Defects  D> 0.8 mm 0 0.3mm D 0.8 mm D< 0.3mm *	D= (L + W) / 2
Foreign Material ( Line shape)	Zone   Acceptable   Class of	L : Long W : Width
Non-uniformity	Visible through 5 %ND filter White, R, G, B and gray 50% pattern.	(Minor)
Dimension Bezel	Outline uneven	(Major) (Minor)
appearance	4.10.7011	



Scratch on the Touch panel	Zone Dimension W> 0.1mm or L >10mm W 0.1 mm L 10mm	Acceptable number  0	Class of Defects Minor	L2 W
Dent on the Touch panel	Zone Dimension D> 0.5 mm  0.3mm D 0.5 mm	Acceptabl number 0 5	e Class of Defects  Minor	L D= (L + W) / 2
Polarizer flaw or leak out resin	Defect is defined	Defect is defined as the active area.		
Corner Chipping	X<3 mm, Y<3 mm, Z< Glass thickness		x y = z	
Edge Chipping	X<3 mm, Y<3 mm, Z< Glass thickness		CT TO THE PARTY OF	
Crack	reject			4



# 12.5 Sampling Condition

Unless otherwise agree in written, the sampling inspection shall be applied to the

incoming inspection of customer.

Lot size: Quantity of shipment lot per model. Sampling type: normal inspection, single sampling

Sampling table: MIL-STD-105E

Inspection level: Level II

		Definition			
Class of	Major	AQL 0.65%	It is a defect that is likely to result in failure or to reduce materially the		
defects	,, , , , , , , , , , , , , , , , , , , ,		usability of the product for the intended function.		
derects	Minor	AQL 1.5%	It is a defect that will not result in functioning problem with deviation classified.		

Note:1.(a)Bright point defect is defined as point defect of R,G,B with area >1/2 pixel respectively

- (b)Dark point defect is defined as visible in full white pattern.
- (c)Definition of distribution of point defect is as follows:
  - -minumum separation between dark point defects should be larger than 5mm.
  - -minumum separation between bright point defects should be larger than 5mm.
- (d)Definition of joined bright point defect and joined dark point defect are as follows:
  - Three or more joined bright point defects must be nil.
  - Three joined dark point defects must be nil.
  - Two Joined dark point is counted as two dark points with 2 pair maximum.
- (e) Line defect is defined as visible by using 5 % ND filter.

Note:2 Luminance measurement for contrast ratio is at the distance  $50\pm$  5cm between the detective head and the panel with ambient illuminance less than 1 lux. Contrast ratio is obtained at optimum view angle



# 13. QUALITY ASSURANCE

# **13.1 Test Condition**

13.1.1 Temperature and Humidity(Ambient Temperature)

Temperature :  $25 \pm 5^{\circ}$ C Humidity :  $65 \pm 5\%$ 

### 13.1.2 Operation

Unless specified otherwise, test will be conducted under function state.

### 13.1.3 Container

Unless specified otherwise, vibration test will be conducted to the product itself without putting it in a container.

# 13.1.4 Test Frequency

In case of related to deterioration such as shock test. It will be conducted only once.

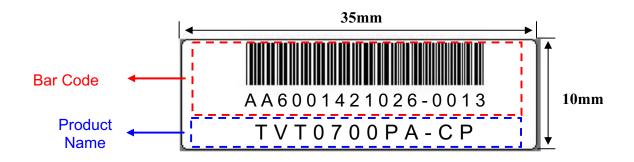
### 13.1.5 Test Method

Reliability Test Item & Level		Test Level	Remark
No.	Test Item		
1.	High Temperature Storage Test	T= 70 ,120hrs after 1 hrs at room temperature and test.	IEC68-2-2
2.	Low Temperature Storage Test	T= -30 ,120hrs after 1 hrs at room temperature and test.	IEC68-2-1
3.	High Temperature Operation Test	T= 60 , 120hrs after 1 hrs at room temperature and test.	IEC68-2-2
4.	Low Temperature Operation Test	T= -20 , 120hrs after 1 hrs at room temperature and test.	IEC68-2-1
5.	High Temperature and High Humidity Operation Test	T= 40 ,90%RH,120hrs after 24 hrs at room temperature and test.	IEC68-2-3
6.	Thermal Cycling Test (No operation)	-20 30min ~60 30 min , 10 Cycles after 24 hrs at room temperature and test.	IEC68-2-14
7.	Vibration Test (No operation)	Frequency :10 ~ 55 H <sub>Z</sub> Amplitude :1.5 mm Sweep time : 11 mins Test Period: 6 Cycles for each direction of X, Y, Z	IEC68-2-6
8.	ESD TEST	Air Discharge : ±15 KV charge & discharge Indirect Contact Discharge : ±8KV charge & discharge	IEC-61000-4-2

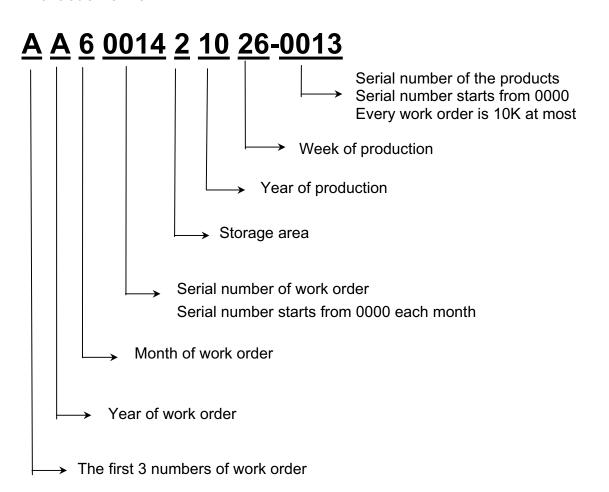


# 14. PRODUCT LABEL DEFINE

# **Product Label style:**



### **BarCode Define:**





**Product Name Define:** 



#### 15. PRECAUTIONS IN USE LCM

#### 5. ASSEMBLY PRECAUTIONS

- You must mount a module using holes arranged in four corners or four sides.
- (2) You should consider the mounting structure so that uneven force (ex. Twisted stress) is not applied to the module. And the case on which a module is mounted should have sufficient strength so that external force is not transmitted directly to the module.
- (3) Do not touch, push or rub the exposed polarizers with glass, tweezers or anything harder than HB pencil lead. And please do not rub with dust clothes with chemical treatment.
- (4) Wipe off saliva or water drops as soon as possible. Their long time contact with polarizer causes deformations and color fading.
- (5) Do not open the case because inside circuits do not have sufficient strength.
- (6) Please do not take a LCD module to pieces and reconstruct it. Resolving and reconstructing modules may cause them not to work well.
- (7) Please do not touch metal frames with bare hands and soiled gloves. A color change of the metal frames can happen during a long preservation of soiled LCD modules.
- (8) Please pay attention to handling lead wire of backlight so that it is not tugged in connecting with inverter.
- (9) Please excessive force or strain to the panel or tail is prohibited.
- (10) Use clean sacks or glove to prevent fingerprints and/or stains left on the panel. Extra attention and carefulness should be taken while handling the glass edge.
- (11) Avoid touching the viewing area before installation /integration.

#### 6. OPERATING PRECAUTIONS

- Please be sure to turn off the power supply before connecting and disconnecting signal input cable.
- (2) Please do not change variable resistance settings in LCD module. They are adjusted to the most suitable value. If they are changed, it might happen LCD does not satisfy the characteristics specification
- (3) Be careful for condensation at sudden temperature change. Condensation makes damage to polarizer or electrical contacted parts. And after fading condensation, smear or spot will occur.
- (4) When fixed patterns are displayed for a long time, remnant image is likely to occur.
- (5) Module has high frequency circuits. Sufficient suppression to the electromagnetic interference shall be done by system manufacturers. Grounding and shielding methods may be important to minimize the interference.
- (6) Please consider that LCD backlight takes longer time to become stable of radiation characteristics in low temperature than in room temperature.
- (7) Touch the panel with your finger or stylus only to assure normal operation. Any sharp edged or hard objects are prohibited.
- (8) Operate the panel in a steady environment. Abrupt variation on temperature and humidity may cause malfunction of the panel.

#### 3. ELECTROSTATIC DISCHARGE CONTROL

- (1) The operator should be grounded whenever he/she comes into contact with the module. Never touch any of the conductive parts such the copper leads on the PCB and the interface terminals with any parts of the human body.
- (2) The modules should be kept in antistatic bags or other containers resistant to static for storage.
- (3) Only properly grounded soldering irons should be used.
- (4) If an electric screwdriver is used, it should be well grounded and shielded from commutator sparks.
- (5) The normal static prevention measures should be observed for work clothes and working benches; for the latter conductive (rubber) mat is recommended
- (6) Since dry air is inductive to statics, a relative humidity of 50-60% is recommended.

#### . STORAGE PRECAUTIONS

- (1) When you store LCDs and touch panel for a long time, it is recommended to keep the temperature between 0°C-40°C without the exposure of sunlight and to keep the humidity less than 90%RH.
- (2) Please do not leave the LCDs and touch panel in the environment of high humidity and high temperature such as 60°C 90%RH
- (3) Please do not leave the LCDs and touch panel in the environment of low temperature; below -20°C.

#### 3. OTHERS

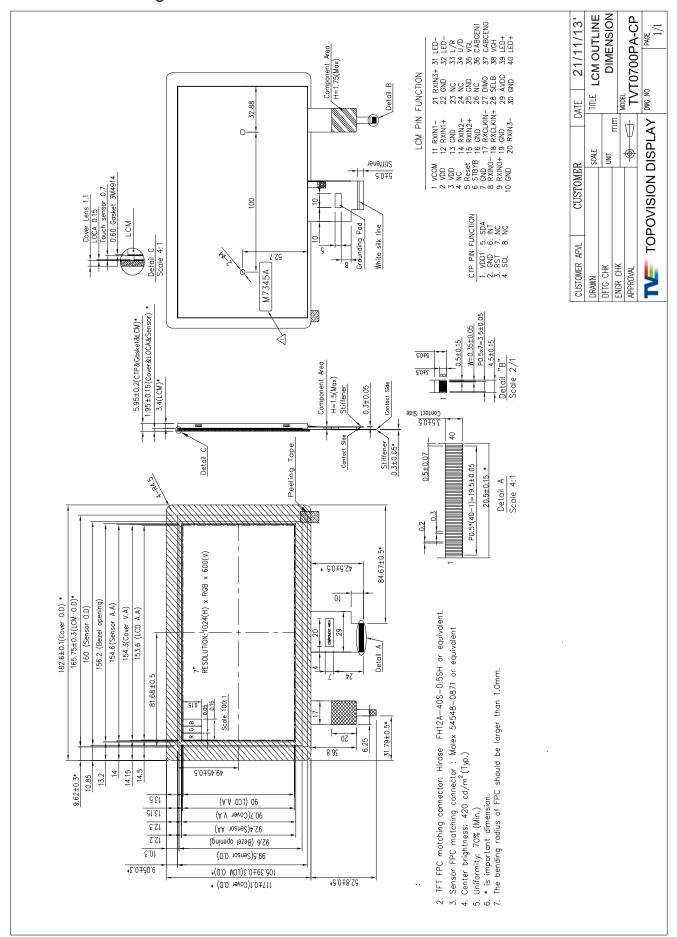
- (1) A strong incident light into LCD panel might cause display characteristics' changing inferior because of polarizer film, color filter, and other materials becoming inferior. Please do not expose LCD module direct sunlight Land strong UV rays
- (2) Please pay attention to a panel side of LCD module not to contact with other materials in preserving it alone.
- (3) For the packaging box, please pay attention to the followings:
- (4) Please do not pile them up more than 5 boxes. (They are not designed so.) And please do not turn over.
- (5) Please handle packaging box with care not to give them sudden shock and vibrations. And also please do not throw them up.
- (6) Packing box and inner case for LCDs are made of cardboard. So please pay attention not to get them wet. (Such like keeping them in high humidity or wet place can occur getting them wet.)

#### 4. LIMITED WARRANTY

Unless otherwise agreed between Topovision and customer, Topovision will replace or repair any of its LCD and LCM which is found to be defective electrically and visually when inspected in accordance with Topovision acceptance standards, for a period on one year from date of shipment. Confirmation of such date shall be based on freight documents. The warranty liability of Topovision is limited to repair and/or replacement on the terms set forth above. Topovision will not responsible for any subsequent or consequential events.

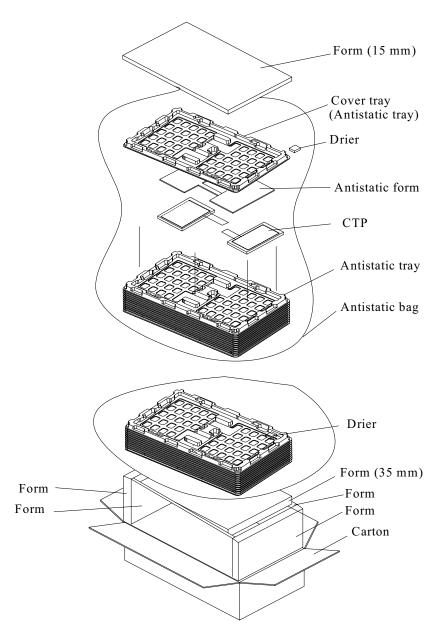


# Outline Drawing





# 17. PACKAGE INFORMATION



### Material

1 Carton + 1 Anti-static bag + Form + Anti-static tray

# Total pcs

1 Antistatic tray = 2 panel pcs

1 Anti-static bag = 16 Anti-static tray + cover tray = 16\*2+0 = 32pcs

1 Carton = 32 pcs

Carton size: 482L x 282W x 279H (mm)

Total Weight = 9 kgw

# 7" PANEL+FPC PACKING